



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-04-26
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SPC560B40L1C6E0X	B95W*FB50BFQ	A	1054	2018-04-26
	Amount	UoM	Unit type	ST ECOPACK Grade
	349	mg	Each	ECOPACK2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10-10-1.4	64	gull wing	
Comment	LQFP 64 10x10x1.4 1			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2016/774 _May 2016	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	B95W*FB508FQ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	32.450	mg	supplier	die	Silicon (Si)	7440-21-3		32.367	mg	997442	92742
				supplier	metallization	Aluminium (Al)	7429-90-5		0.035	mg	1079	100
				supplier	Passivation	Silicon Oxide	7631-86-9		0.048	mg	1479	138
Leadframe	M-004 Copper and its alloys	102.144	mg	supplier	alloy	Copper (Cu)	7440-50-8		99.545	mg	974556	285229
				supplier	alloy	Iron (Fe)	7439-89-6		0.100	mg	978	286
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.030	mg	294	86
Die attach		4.434	mg	supplier	metallization	Silver (Ag)	7440-22-4		2.469	mg	24172	7074
				supplier	glue or tape (choose)	Silver (Ag)	7440-22-4		3.991	mg	900090	11436
				supplier	glue or tape	Isobornyl Methacrylate	7534-94-3		0.244	mg	55029	699
Bonding wires	M-004 Copper and its alloys	0.450	mg	supplier	glue or tape	Bismaleimide resin	Proprietary		0.177	mg	39919	507
				supplier	glue or tape	spacer polymer	Proprietary		0.022	mg	4962	63
				supplier	wire	Copper (Cu)	7440-50-8		0.441	mg	980000	1264
Encapsulation	M-011 Other inorganic materials	205.957	mg	supplier	wire	Palladium (Pd)	7440-05-3		0.008	mg	17778	23
				supplier	wire	Silver (Ag)	7440-22-4		0.001	mg	2222	3
				supplier	mold compound	Silica, vitreous	60676-86-0		179.388	mg	870997	514006
connections coating	Solder	3.565	mg	supplier	mold compound	Epoxy Resin	85954-11-6		16.477	mg	80002	47212
				supplier	mold compound	Phenol Resin	26834-02-6		8.238	mg	39999	23605
				supplier	mold compound	Carbon black	1333-86-4		1.030	mg	5001	2951
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.824	mg	4001	2361
				supplier	solder alloy	Tin (Sn)	7440-31-5		3.565	mg	1000000	10215